

## Abstract

5 A manufacturing method for a semiconductor device using a wire  
bonding method using a metal wire. In the wire bonding method, an impact  
load applied when a metal ball formed at the tip of the metal wire by electric  
10 discharge is brought into contact with a terminal electrode of a semiconductor  
device is smaller than a static load applied after the metal ball is brought into  
contact with the terminal electrode. The method makes it possible to prevent  
an element or wiring from being damaged while securing the pressure  
15 necessary for bonding the metal ball to the terminal electrode even when the  
terminal electrode is placed on the element or the wiring.

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